

Patent Abstracts of Japan

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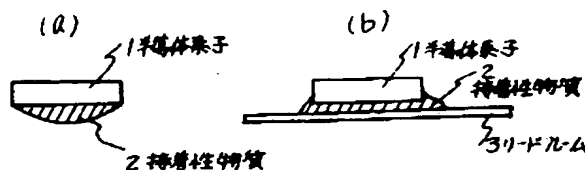
APPLICATION DATE : 24-07-84  
APPLICATION NUMBER : 59153609

APPLICANT : NEC CORP;

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TITLE : METHOD FOR FIXING OF  
SEMICONDUCTOR ELEMENT



ABSTRACT : PURPOSE: To improve the strength of bonding and the accuracy of fixing position by fixing a semiconductor element while covering its backsurface with adhesive material and placing it on its top of lead frame and stem.

CONSTITUTION: On a back surface of a semiconductor element 1, an adhesive substance 2 such as resin, an insulating paste or a conductive paste in which Ag and Cu are mixed is applied and the element is put on a lead frame 3. By a heat treatment, the semiconductor element 1 is attached to the lead frame 3. Consequently, a quantity of adhesive substance can be controlled and the semiconductor element does not incline. Also a slip of the positions between the element and adhesive substance does not occur and a decline of adhesive strength and exfoliation of elements due to said slip can be prevented.

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